

Challenge the next generation with ceramics!

Plasma-resistant thermal spray coating

More and more, it seems that semiconductor parts have been upsizing according with upsizing of wafer size from 8 to 12 inches. Those tendencies make us difficult to manufacture them by using ceramics materials. We are suggesting the aluminum metal materials which are coated ceramics by our thermal spray method. One of our strong point is that our coating membrane is very minute, and has a character of high plasmaresistance. In addition, we can provide the high temperature specifications type whose membrane dose not come off under high temperature of 500 degrees.



Characteristics

Micro structure of membrane (cross section) NC method Conventional method



Materials properties

		NC method	Conventional method
Coherence	Y ₂ O ₃	Ø	Δ
force	AI_2O_3	Ø	0
Abrasion	Y ₂ O ₃	0	Δ
	AI_2O_3	Ø	0
Hardness	Y_2O_3	0	Δ
	AI_2O_3	Ø	0
Density	Y_2O_3	Ø	Δ
	Al ₂ O ₃	Ø	0

Use example

OVarious semiconductor chamber materials (Especially, for chamber parts) OAbrasion-resistant parts (Rolled materials, etc) OElectro Static Chuck

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